


BOSCO Printed Circuits (Pty Ltd)**Manufacturing Capabilities**

Base Laminate Materials Standards: IPC4101/21: Flammability UL 94 V-0 RoHS Compliant  Click here for Aluminium Base Material Data Sheet Click here FR-4 Base Material Data Sheet	Aluminium Substrate Pcb's (5052 Alu Alloy)			
	Thickness	Di-Electric Thickness	Finished Copper (Cu) Thickness	Thermal Conductivity W/m.K
	1.5mm	100 µm	35/00	1.5 (± 0.2W/m*k)
	FR - 4 Epoxy Glass Laminate			
	Thickness	Finished Copper (Cu) Thickness		Tg °C
	0.8mm	35/00	35/35 ~	135 °C (±5)
	1.0mm	35/00	35/35 * 70/70	135 °C (±5)
	1.2mm	35/00	35/35 ~	135 °C (±5)
	* 1.55mm	35/00	35/35 ~	135 °C (±5)
	1.6mm	70/00	70/70 ~	135 °C (±5)
* 2.4mm	35/35	~ ~	135 °C (±5)	
* 3.2mm	35/35	~ ~	135 °C (±5)	
Note: Laminate Thickness Includes Copper Cladding. D/S THP Pcb's will be Electroplated with an additional > 20 microns of copper each side. For Pcb's with HAL Surface Finish - add 6-20 microns Tin on each side * Subject to material stocks on hand				
Maximum Pcb Size	Maximum Pcb Size		450 x 540mm	
	Maximum Pcb Size for Edge Connector Side		340mm	
	Maximum Pcb Size for Bare Board Test		320 x 410mm	
Minimum Finished Hole Diameter	0.4mm	For PTH - Up to 1.6mm max material thickness		
	0.3mm	<i>For PTH - Up to 1.6mm max material thickness BUT subject to prior consultation with the Technical Director & BBT (Bare Board Test / Electrical Test is Mandatory)</i>		
	0.6mm	PTH - Material thickness > 2.0mm		
	0.5mm	Non-PTH - Up to 3.2mm max material thickness		
Tolerance of Finished Hole Diameters	- 0.00mm : + 0.05mm	THP Holes : 0.4 - 1.5mm Diameter		
	-0.00 mm : + 0.1mm	THP Holes : > 1.5mm Diameter		
	±0.05mm	Non-THP Holes : 0.5 - 1.6mm Diameter		
	±0.05mm	Non-THP Holes : > 1.6mm Diameter		
	±0.15mm	Routed Holes > 6.0mm		
Minimum Annular Ring (i.e. by Pattern Registration)	0.08mm	PTH Hole		
	0.15mm	Non-PTH Hole		
	0.3mm	PTH Hole for 70 µm Copper Thickness		
	0.3mm	Non-PTH Hole for 70 µm Copper Thickness		

Minimum Conductor (Track) Widths and Spacing for THP (Through Hole Plated Pcb's)	Base Cu Thickness	Plated Cu Thickness	Finished Cu Thickness	Minimum Conductor (Trace) Width	Minimum Conductor (Trace) Space
	17 μm	20 μm	37 μm	* 0.18mm (7 Mil)	* 0.18mm (7 Mil)
	17 μm	20 μm	37 μm	0.2mm (8 Mil)	0.2mm (8 Mil)
	35 μm	20 μm	55 μm	* 0.15mm (7 Mil)	* 0.15mm (7 Mil)
	70 μm	20 μm	90 μm	0.2mm (8 Mil)	0.2mm (8 Mil)
* Subject to prior consultation & BBT (Bare Board Test / Electrical Test is Mandatory)					
Minimum Conductor (Track) Widths and Spacing for S/S (Single Sided Pcb's)	Base Cu Thickness	Plated Cu Thickness	Finished Cu Thickness	Minimum Conductor (Trace) Width	Minimum Conductor (Trace) Space
	35 μm	~	35 μm	* 0.18mm (7 Mil)	0.18mm (7 Mil)
	35 μm	~	35 μm	0.2mm (8 Mil)	0.2mm (8 Mil)
	70 μm	~	70 μm	0.3mm (12 Mil)	0.3mm (12 Mil)
* Subject to prior consultation & BBT (Bare Board Test / Electrical Test is Mandatory)					
Land (Pad) Size by Design	Minimum Land (Pad) Size: Component Hole Diameter +0.4mm (i.e. Annular Ring 0.2mm / 10 Mil)				
Landless Hole to Conductor Spacing	Minimum Via Land (Pad) Size: Via Hole Diameter +0.3mm (i.e. Annular Ring 0.15mm / 6 Mil)				
Minimum Distance of ANY Feature from Edges of the Routed Pcb including the Pcb Edges supplied on V-Scored Panels	0.2mm (8 Mil)		Preferred		
	0.175mm (7 Mil)		Bare Board Test / Electrical Test is Mandatory		
	1.2 - 1.6mm Thickness Material			0.3mm	Routed
	1.2 - 1.6mm Thickness Material			0.4mm	V-Scored
	2.4 & 3.2mm Thickness Material			0.6mm	V-Scored
	0.8 - 1.0mm Thickness Material			0.3mm	Routed
Minimum Distance between Hole Walls	0.3mm [12 Mil]				
Minimum Distance between Holes and Pcb Edge / Panel Edge / Cut-outs (Excluding Edge Connectors)	1.0mm (0.3mm subject to Consultation with the Technical Director)				
Minimum Slot Width	1.0mm (0.8mm subject to Consultation with the Technical Director)				
Minimum Radius on internal Cut-outs	1.2mm (0.5mm Subject to Consultation with the Technical Director)				
Routing Diameter	2.4mm Standard				
Routing Tolerance	$\pm 0.1\text{mm}$ This applies to internal cutouts as well as for the CNC Routed Pcb Profile				
Plating Thickness	Pattern Plated & THP Copper			20 μm Minimum (25 μm Normal)	
	Gold over Nickel Edge Connector			0.8 μm Minimum (1.0 μm Normal)	
	Nickel (for Edge Connector)			2.5 μm	
Surface Finishes	Solder Hot Air Level (HAL - Lead Free)		6 - 20 μ	$\pm 6 \mu\text{m}$ Minimum	

Solder Resist (Photo-Imagable)	Curtain Coat	Green	
	Screen Print Coat	Blue, Red, White, Black & Yellow	
	Minimum Resist Thicknes	10 µm (Measured at Conductor Knee)	
Minumum Resist Clearance around Lands / Pads	0.1mm	Min. Solder Dam	0.2mm
Notation Ink (Legend, Ident)	Colours	White, Black	
	Barcode & Number Serialization	Offered for White Only	
Conductive Carbon	Used for Keypads and other Carbon Contact purposes		
	Surface Resistance	< 35 ohm / Square	
	Loop Resistance	< 75 ohm	
	Min. Thickness	15 µ	
Temporary Solder Resist	(Peelable Blue Mask)	Note: Maximum Hole Diameter for Hole Tenting is 1.10mm	
Electrical Bare Board Testing (BBT)	Minimum Pitch	0.3mm (12 Mil) (By Flying Probe : 0.15mm)	
	Test Voltage	10 Volts	
	Isolation	2 Mohm	
V-Scoring Click to See our V-Score Specification : Document No.VS001 Rev 1 2016	Web Thickness	0.3mm	Min 0.27mm : Max 0.35mm
	V-Score Angle	30°	
	Nominal Breaking Point (on each side of the Pcb)	Tolerance	0.1 - 0.15mm
Quality	ISO 9001 : 2008 ANSI/IPC A 600 (ANSI: American National Standards Institute) (IPC: Institute for Interconnecting and Packaging Electronic Circuits)		
RoHS Compliance	All Pcb's manufactured and Supplied by Bosco are RoHS Compliant		
<i>Please consult with our Technical Director for any other special requirements or requests.</i>			

Continued on next Page

Non Standard Base Materials that are not available from Bosco but are available from our offshore Pcb Manufacturer

Laminates	Unit	Bosco Standard	Non-Standard - Available Offshore Only
FR-4 Base Material:			
Available Thicknesses S/S & D/S	mm	0.8 (± 0.1) ; 1.0 (± 0.13) ; 1.2 (± 0.13) ; 1.55 (± 0.13) ; 2.4 (± 0.23) ; 3.2 (± 0.23)	0.35 (± 0.05)
Available Copper Thickness	μm	35 ; 70	105
Glass Transition Temperature - Tg	$^{\circ}\text{C}$	135 (± 5)	170
Aluminium Substrate Base Material:			
Available Thicknesses S/S & D/S	mm	1.5 (± 0.13)	1.0 (± 0.13) ; 2.0 (± 0.18)
Available Thicknesses D/S (Offshore Only)	mm	~	0.8 (± 0.1) ; 1.0 (± 0.13) ; 1.5 (± 0.13) ; 2.0 (± 0.18)
Availabel Copper Thicknesses	μm	35	70
Dielectric Thickness	μm	100	150
Glass Transition Temperature - Tg	$^{\circ}\text{C}$	≥ 110	≥ 110
THERMAL Conductivity - W/m*K	W/m*K	1.5 (± 0.2 W/m*K)	2.0 ; 3.0 (± 0.3 W/m*K)

